Bipolar Power Transistors 40 V, 3.0 A, Low V_{CE(sat)} NPN Transistor

ON Semiconductor's e^2 PowerEdge family of low $V_{CE(sat)}$ transistors are surface mount devices featuring ultra low saturation voltage ($V_{CE(sat)}$) and high current gain capability. These are designed for use in low voltage, high speed switching applications where affordable efficient energy control is important.

Typical applications are DC–DC converters and power management in portable and battery powered products such as cellular and cordless phones, PDAs, computers, printers, digital cameras and MP3 players. Other applications are low voltage motor controls in mass storage products such as disc drives and tape drives. In the automotive industry they can be used in air bag deployment and in the instrument cluster. The high current gain allows e²PowerEdge devices to be driven directly from PMU's control outputs, and the Linear Gain (Beta) makes them ideal components in analog amplifiers.

Features

- Complement to NSS40300MZ4 Series
- NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS (T_C = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
Collector–Emitter Voltage	V _{CEO}	40	Vdc
Collector-Base Voltage	V _{CB}	40	Vdc
Emitter-Base Voltage	V _{EB}	6.0	Vdc
Base Current – Continuous	I _B	1.0	Adc
Collector Current – Continuous	I _C	3.0	Adc
Collector Current – Peak	I _{CM}	5.0	Adc
Total Power Dissipation Total P _D @ T _A = 25°C (Note 1) Total P _D @ T _A = 25°C (Note 2)	P _D	2.0 0.80	W
Operating and Storage Junction Temperature Range	T _J , T _{stg}	-55 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

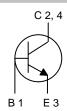
- 1. Mounted on 1" sq. (645 sq. mm) Collector pad on FR-4 bd material.
- 2. Mounted on 0.012" sq. (7.6 sq. mm) Collector pad on FR-4 bd material.



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NPN TRANSISTOR 3.0 AMPERES 40 VOLTS, 2.0 WATTS



Schematic



SOT-223 CASE 318E STYLE 1

MARKING DIAGRAM



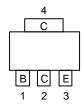
A = Assembly Location

Y Year W = Wo

= Work Week

40301 = Specific Device Code ■ Pb–Free Package

PIN ASSIGNMENT



Top View Pinout

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Case Junction-to-Ambient on 1" sq. (645 sq. mm) Collector pad on FR-4 bd material Junction-to-Ambient on 0.012" sq. (7.6 sq. mm) Collector pad on FR-4 bd material	$egin{array}{l} R_{ hetaJA} \ R_{ hetaJA} \end{array}$	64 155	°C/W
Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 5 seconds	T_L	260	°C

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS	<u>'</u>		1	1	
Collector–Emitter Sustaining Voltage (I _C = 10 mAdc, I _B = 0 Adc)	V _{CEO(sus)}	40	_	-	Vdc
Emitter–Base Voltage ($I_E = 50 \mu Adc$, $I_C = 0 Adc$)	V _{EBO}	6.0	_	-	Vdc
Collector Cutoff Current (V _{CB} = 40 Vdc)	I _{CBO}	-	_	100	nAdc
Emitter Cutoff Current (V _{BE} = 6.0 Vdc)	I _{EBO}	-	_	100	nAdc
ON CHARACTERISTICS (Note 3)					
Collector–Emitter Saturation Voltage ($I_C = 0.5 \text{ Adc}$, $I_B = 50 \text{ mAdc}$) ($I_C = 1.0 \text{ Adc}$, $I_B = 20 \text{ mAdc}$) ($I_C = 3.0 \text{ Adc}$, $I_B = 0.3 \text{ Adc}$)	V _{CE(sat)}	- - -	- - -	0.050 0.100 0.200	Vdc
Base–Emitter Saturation Voltage (I _C = 1.0 Adc, I _B = 0.1 Adc)	V _{BE(sat)}	-	_	1.0	Vdc
Base–Emitter On Voltage (I _C = 1.0 Adc, V _{CE} = 2.0 Vdc)	V _{BE(on)}	-	_	0.9	Vdc
DC Current Gain $(I_C = 0.5 \text{ Adc}, V_{CE} = 1.0 \text{ Vdc})$ $(I_C = 1.0 \text{ Adc}, V_{CE} = 1.0 \text{ Vdc})$ $(I_C = 3.0 \text{ Adc}, V_{CE} = 1.0 \text{ Vdc})$	h _{FE}	220 200 100	- - -	500	_
DYNAMIC CHARACTERISTICS					
Output Capacitance (V _{CB} = 10 Vdc, f = 1.0 MHz)	C _{ob}	-	25	-	pF
Input Capacitance (V _{EB} = 5.0 Vdc, f = 1.0 MHz)	C _{ib}	-	170	-	pF
Current–Gain – Bandwidth Product (Note 4) (I _C = 500 mA, V _{CE} = 10 V, F _{test} = 1.0 MHz)	f _T	_	215	_	MHz

^{3.} Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.

^{4.} $f_T = |h_{FE}| \bullet f_{test}$

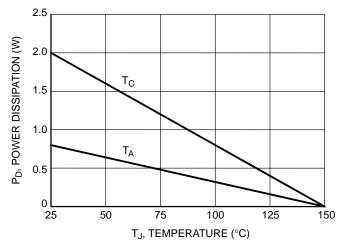


Figure 1. Power Derating

TYPICAL CHARACTERISTICS

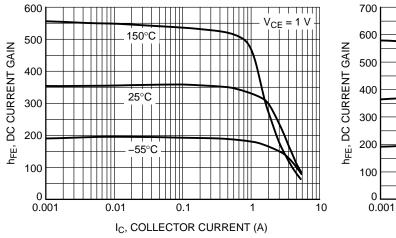


Figure 2. DC Current Gain

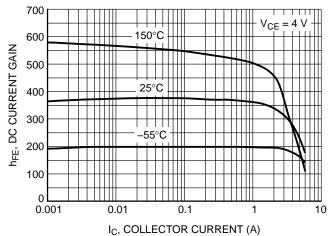


Figure 3. DC Current Gain

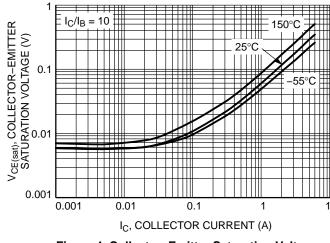


Figure 4. Collector-Emitter Saturation Voltage

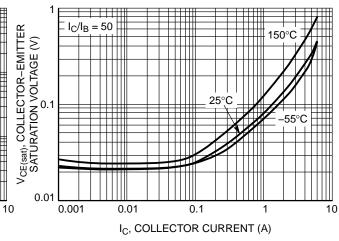


Figure 5. Collector-Emitter Saturation Voltage

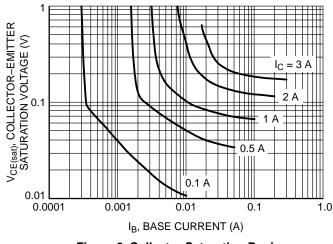


Figure 6. Collector Saturation Region

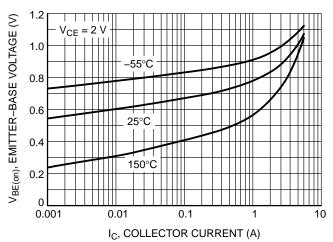


Figure 7. V_{BE(on)} Voltage

TYPICAL CHARACTERISTICS

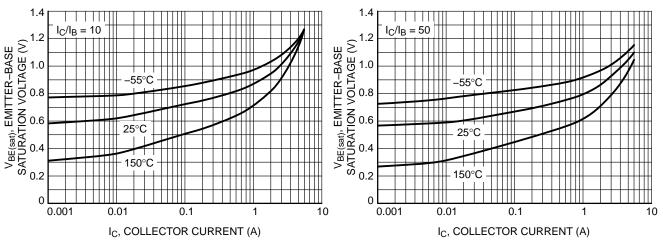


Figure 8. Base-Emitter Saturation Voltage

Figure 9. Base-Emitter Saturation Voltage

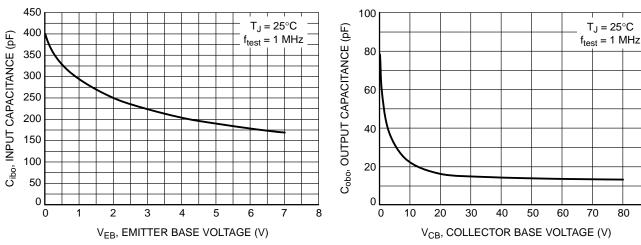


Figure 10. Input Capacitance

Figure 11. Output Capacitance

80

90

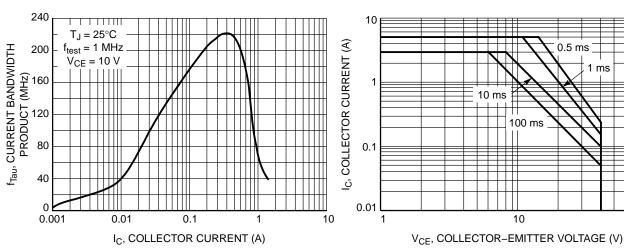


Figure 12. Current-Gain Bandwidth Product

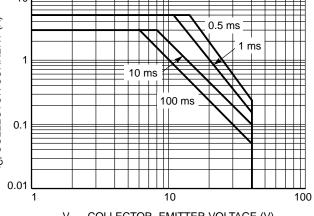


Figure 13. Safe Operating Area

ORDERING INFORMATION

Device	Package	Shipping [†]
NSS40301MZ4T1G	SOT-223 (Pb-Free)	1,000 / Tape & Reel
NSV40301MZ4T1G*	SOT-223 (Pb-Free)	1,000 / Tape & Reel
NSS40301MZ4T3G	SOT-223 (Pb-Free)	4,000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
*NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q101 Qualified and PPAP

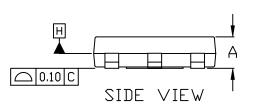
Capable

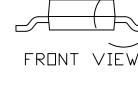


SOT-223 (TO-261) CASE 318E-04 ISSUE R

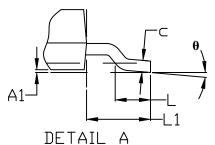
DATE 02 OCT 2018







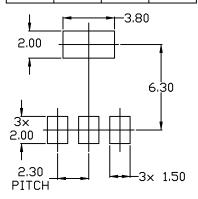
SEE DETAIL A



NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. DIMENSIONS D & E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
 MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.200MM PER SIDE.
- 4. DATUMS A AND B ARE DETERMINED AT DATUM H.
- 5. ALLIS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT OF THE PACKAGE BODY.
- 6. POSITIONAL TOLERANCE APPLIES TO DIMENSIONS 6 AND 61.

	MILLIMETERS			
DIM	MIN.	N□M.	MAX.	
Α	1.50	1.63	1.75	
A1	0.02	0.06	0.10	
b	0.60	0.75	0.89	
b1	2.90	3.06	3.20	
c	0.24	0.29	0.35	
D	6.30	6.50	6.70	
E	3.30	3.50	3.70	
е	2.30 BSC			
L	0.20			
L1	1.50	1.75	2.00	
He	6.70	7.00	7.30	
θ	0*		10°	



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SOT-223 (TO-261) CASE 318E-04 ISSUE R

DATE 02 OCT 2018

STYLE 1: PIN 1. BASE 2. COLLECTOR 3. EMITTER 4. COLLECTOR	STYLE 2: PIN 1. ANODE 2. CATHODE 3. NC 4. CATHODE	STYLE 3: PIN 1. GATE 2. DRAIN 3. SOURCE 4. DRAIN	STYLE 4: PIN 1. SOURCE 2. DRAIN 3. GATE 4. DRAIN	STYLE 5: PIN 1. DRAIN 2. GATE 3. SOURCE 4. GATE
STYLE 6: PIN 1. RETURN 2. INPUT 3. OUTPUT 4. INPUT	STYLE 7: PIN 1. ANODE 1 2. CATHODE 3. ANODE 2 4. CATHODE	4. DHAIN STYLE 8: CANCELLED	STYLE 9: PIN 1. INPUT 2. GROUND 3. LOGIC 4. GROUND	STYLE 10: PIN 1. CATHODE 2. ANODE 3. GATE 4. ANODE
STYLE 11: PIN 1. MT 1 2. MT 2 3. GATE 4. MT 2	STYLE 12: PIN 1. INPUT 2. OUTPUT 3. NC 4. OUTPUT	STYLE 13: PIN 1. GATE 2. COLLECTOR 3. EMITTER 4. COLLECTOR		

GENERIC MARKING DIAGRAM*



A = Assembly Location

Y = Year W = Work Week

XXXXX = Specific Device Code

= Pb-Free Package

(Note: Microdot may be in either location)
*This information is generic. Please refer to
device data sheet for actual part marking.
Pb-Free indicator, "G" or microdot "•", may
or may not be present. Some products may
not follow the Generic Marking.

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